EEMF6315 - Advanced Electronic Packaging Technologies

EEMF 6315 Advanced Electronic Packaging Technologies (3 semester credit hours) Electrical design and analysis- signal and power integrity, thermal designs at chip-package-board level, cooling solutions, thermo-mechanical designs and interface stress analysis. Reliability testing and failure modes. Electronic packaging materials, properties and characterization, chip-package interconnection technologies, wafer scale and 3D packaging, encapsulation techniques, multi-chip modules and system in package-heterogeneous integration technologies. Design for performance, reliability, and manufacturing. (3-0) Y